

STM32F7 Series Flash-memory dual-bank mode, software expansion for STM32Cube

Data brief

Features

- Flash dual-bank
- Read while write
- Dual boot
- Bank swap
- Write protections
- Safety upgrade

Description

The X-CUBE-DBANK-F7 firmware is intended to describe the STM32F7 Flash-memory dual-bank capabilities.

This firmware package is provided with three embedded software examples that cover the read while write (RWW), the dual boot and the device's performance and consumption with Flash-memory in dual-bank mode.

This package complements the STM32CubeF7 firmware Flash-memory examples and gives more details about the dual-bank mode.

The X-CUBE-DBANK-F7 firmware is developed with STM32Cube embedded software. It uses the IAR Embedded Workbench[®] for ARM[®] (EWARM) by IAR systems[®], the Microcontroller Development Kit for ARM[®] (MDK-ARM) by Keil[®] and the SW4STM32 tool chains and can be easily tailored for any another tool chain.

For more details refer to the application note AN4826.

1 Revision history

Table 1. Document revision history

Date	Revision	Changes
03-Jun-2016	1	Initial release.

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